

photodetecting element for receiving each of a plurality of the laser beams radiated from each of the laser chips, and a package for enclosing the light source and the photodetecting element, wherein the surface where a plurality of the semiconductor laser chips are mounted is substantially perpendicular to the tracking servo direction.

AI  
A laser module comprising a semiconductor plate, a mount surface for laser chips provided on the semiconductor plate, a plurality of semiconductor laser chips mounted on the mount surface for the laser chips, a reflection plane provided on the semiconductor plate for reflecting laser beams radiated from a plurality of the semiconductor laser chips, and a photodetecting element, which is provided on the semiconductor plate, for receiving the laser beams radiated from a plurality of the semiconductor laser chips, wherein the photodetecting elements are arranged at both sides of a plurality of the semiconductor laser chips in a direction where a plurality of the semiconductor laser chips are arranged.

A laser module comprising a package for enclosing the semiconductor plate, wherein the outline of the package in a plane perpendicular to a direction, where the laser beam is radiated from the package, has an approximate rectangular shape in a degree where its long direction and short direction can be distinguished, and a plurality of semiconductor laser chips and the photodetecting element are arranged in a direction of the short side of the package.

A<sup>1</sup>  
A laser module comprising a semiconductor plate, a mount surface for laser chips provided on the semiconductor plate, a plurality of semiconductor laser chips mounted on the mount surface for the laser chips, a reflection plane provided on the semiconductor plate for reflecting laser beams radiated from a plurality of the semiconductor laser chips, and a photodetecting element, which is provided on the semiconductor plate, for receiving the laser beams radiated from a plurality of the semiconductor laser chips, wherein the semiconductor plate includes a plurality of pads for electrically connecting with an external electronic circuit and a plurality of the pads are arranged along a side of the semiconductor plate parallel with a direction where a plurality of the semiconductor laser chips are arranged.

A laser module comprising a plurality of the lead wires for electrically connecting a package for enclosing the semiconductor plate with an external electronic circuit, wherein the outline of the package in a plane perpendicular to a direction, where the laser beam is radiated from the package, has the approximate rectangular shape in a degree where its long direction and short direction can be distinguished, and a plurality of the lead wires are arranged in a direction of the short side of the package.--

IN THE CLAIMS:

Please amend claims 1 and 6 as follows: